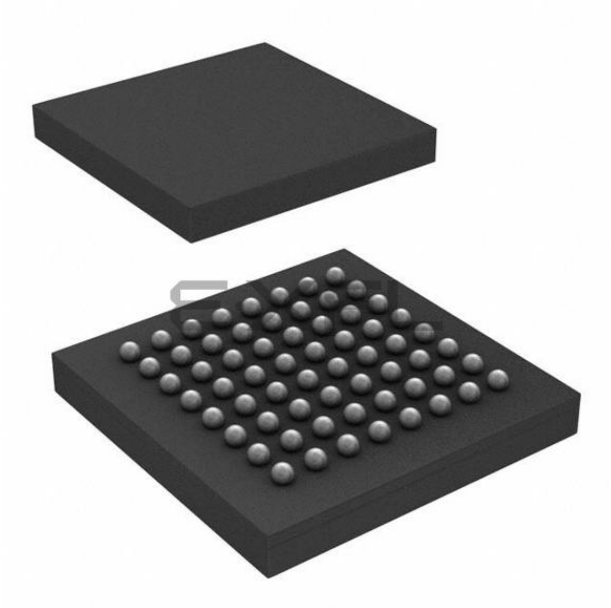
Microchip Technology - ATSAML21J17B-UUT Datasheet



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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M0+
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	I²C, LINbus, SCI, SPI, UART/USART, USB
Peripherals	DMA, POR, PWM, WDT
Number of I/O	51
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	1.62V ~ 3.63V
Data Converters	A/D 20x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-XFBGA, WLCSP
Supplier Device Package	64-WLCSP (3.58x3.28)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atsaml21j17b-uut

- Static and Dynamic Power Gating Architecture
- Battery backup support
- Two Performance Levels
- Embedded Buck/LDO regulator supporting on-the-fly selection

- Peripherals
  - 16-channel Direct Memory Access Controller (DMAC)
  - 12-channel Event System
  - Up to five 16-bit Timer/Counters (TC) including one low-power TC, each configurable as:
    - 16-bit TC with two compare/capture channels
    - 8-bit TC with two compare/capture channels
    - 32-bit TC with two compare/capture channels, by using two TCs
  - Two 24-bit and one 16-bit Timer/Counters for Control (TCC), with extended functions:
    - Up to four compare channels with optional complementary output
    - Generation of synchronized pulse width modulation (PWM) pattern across port pins
    - Deterministic fault protection, fast decay and configurable dead-time between complementary output
    - Dithering that increase resolution with up to 5 bit and reduce quantization error
  - 32-bit Real Time Counter (RTC) with clock/calendar function
  - Watchdog Timer (WDT)
  - CRC-32 generator
  - One full-speed (12Mbps) Universal Serial Bus (USB) 2.0 interface
    - Embedded host and device function
    - Eight endpoints
  - Up to six Serial Communication Interfaces (SERCOM) including one low-power SERCOM, each configurable to operate as either:
    - USART with full-duplex and single-wire half-duplex configuration
    - I^2C up to 3.4MHz
    - SPI
    - LIN slave
  - One AES encryption engine
  - One True Random Generator (TRNG)
  - One Configurable Custom Logic (CCL)
  - One 12-bit, 1MSPS Analog-to-Digital Converter (ADC) with up to 20 channels
    - Differential and single-ended input
    - Automatic offset and gain error compensation
    - Oversampling and decimation in hardware to support 13-, 14-, 15-, or 16-bit resolution
  - Two 12-bit, 1MSPS Dual Output Digital-to-Analog Converter (DAC)
  - Two Analog Comparators (AC) with window compare function
  - Three Operational Amplifiers (OPAMP)
  - Peripheral Touch Controller (PTC)
    - 169-Channel capacitive touch and proximity sensing
    - Wake-up on touch in standby mode

- Oscillators
  - 32.768kHz crystal oscillator (XOSC32K)

  - 0.4-32MHz crystal oscillator (XOSC)
  - 32.768kHz internal oscillator (OSC32K)
  - 32.768kHz ultra-low-power internal oscillator (OSCULP32K)
  - 16/12/8/4MHz high-accuracy internal oscillator (OSC16M)
  - 48MHz Digital Frequency Locked Loop (DFLL48M)
  - 96MHz Fractional Digital Phased Locked Loop (FDPLL96M)
- I/O
  - Up to 51 programmable I/O pins
- Easy migration from SAM D family
- Packages
  - 64-pin TQFP, QFN, WLCSP
  - 48-pin TQFP, QFN
  - 32-pin TQFP, QFN
- Operating Voltage
  - 1.62V – 3.63V

Table of Contents

1. Description

Atmel® | SMART SAM L21 is a series of Ultra low-power microcontrollers using the 32-bit ARM® Cortex®-M0+ processor, and ranging from 32- to 64-pins with up to 256KB Flash and 40KB of SRAM. The SAM L21 devices operate at a maximum frequency of 48MHz and reach 2.46 CoreMark®/MHz. They are designed for simple and intuitive migration with identical peripheral modules, hex compatible code, identical linear address map and pin compatible migration paths between all devices in the product series. All devices include intelligent and flexible peripherals, Atmel Event System for inter-peripheral signaling, and support for capacitive touch button, slider and wheel user interfaces.

The Atmel SAM L21 devices provide the following features: In-system programmable Flash, 16-channel direct memory access (DMA) controller, 12-channel Event System, programmable interrupt controller, up to 51 programmable I/O pins, 32-bit real-time clock and calendar, up to five 16-bit Timer/Counters (TC) and three Timer/Counters for Control (TCC) where each TC/TCC can be configured to perform frequency and waveform generation, accurate program execution timing or input capture with time and frequency measurement of digital signals. The TCs can operate in 8- or 16-bit mode, selected TCs can be cascaded to form a 32-bit TC, and three timer/counters have extended functions optimized for motor, lighting and other control applications. Two TCC can operate in 24-bit mode, the third TCC can operate in 16-bit mode. The series provide one full-speed USB 2.0 embedded host and device interface; up to six Serial Communication Modules (SERCOM) that each can be configured to act as an USART, UART, SPI, I^2C up to 3.4MHz, SMBus, PMBus, and LIN slave; up to twenty channel 1MSPS 12-bit ADC with programmable gain and optional oversampling and decimation supporting up to 16-bit resolution, two 12-bit 1MSPS DACs, two analog comparators with window mode, three independent cascadable OPAMPs supporting internal connection with others analog features, Peripheral Touch Controller supporting up to 192 buttons, sliders, wheels and proximity sensing; programmable Watchdog Timer, brown-out detector and power-on reset and two-pin Serial Wire Debug (SWD) program and debug interface.

All devices have accurate and low-power external and internal oscillators. All oscillators can be used as a source for the system clock. Different clock domains can be independently configured to run at different frequencies, enabling power saving by running each peripheral at its optimal clock frequency, and thus maintaining a high CPU frequency while reducing power consumption.

The SAM L21 devices have four software-selectable sleep modes, idle, standby, backup and off. In idle mode the CPU is stopped while all other functions can be kept running. In standby all clocks and functions are stopped except those selected to continue running. In this mode all RAMs and logic contents are retained. The device supports SleepWalking. This feature allows the peripheral to wake up from sleep based on predefined conditions, and thus allows some internal operation like DMA transfer and/or the CPU to wake up only when needed, e.g. when a threshold is crossed or a result is ready. The Event System supports synchronous and asynchronous events, allowing peripherals to receive, react to and send events even in standby mode.

The SAM L21 devices have two software-selectable performance levels (PL0 and PL2) allowing the user to scale the lowest core voltage level that will support the operating frequency. To further minimize consumption, specifically leakage dissipation, the SAM L21 devices utilizes power domain gating technique with retention to turn off some logic area while keeping its logic state. This technique is fully handled by hardware.

The Flash program memory can be reprogrammed in-system through the SWD interface. The same interface can be used for nonintrusive on-chip debugging of application code. A boot loader running in the device can use any communication interface to download and upgrade the application program in the Flash memory.

	SAM L21J	SAM L21G	SAM L21E
Real-Time Counter (RTC)	Yes	Yes	Yes
RTC alarms	1	1	1
RTC compare values	One 32-bit value or two 16-bit values	One 32-bit value or two 16-bit values	One 32-bit value or two 16-bit values
External Interrupt lines	16	16	16
Peripheral Touch Controller (PTC) channels (X- x Y-Lines) for mutual capacitance [(2)]	169 (13x13)	81 (9x9)	42 (7x6)
Peripheral Touch Controller (PTC) channels for self capacitance (Y-Lines only) [(3)]	16	10	7
Maximum CPU frequency	48MHz		
Packages	QFN TQFP WLCSP[(4)]	QFN TQFP	QFN TQFP
Oscillators	32.768kHz crystal oscillator (XOSC32K) 0.4-32MHz crystal oscillator (XOSC) 32.768kHz internal oscillator (OSC32K) 32KHz ultra-low-power internal oscillator (OSCULP32K) 16/12/8/4MHz high-accuracy internal oscillator (OSC16M) 48MHz Digital Frequency Locked Loop (DFLL48M) 96MHz Fractional Digital Phased Locked Loop (FDPLL96M)		
Event System channels	12	12	12
SW Debug Interface	Yes	Yes	Yes
Watchdog Timer (WDT)	Yes	Yes	Yes

Note:

1. For SAM L21E and SAM L21G, only TC0, TC1 and TC4 are available.
2. The number of X- and Y-lines depends on the configuration of the device, as some I/O lines can be configured as either X-lines or Y-lines. Refer to *Multiplexed Signals* for details. The number in the Configuration Summary is the maximum number of channels that can be obtained.

3.2. SAM L21G

Table 3-2. SAM L21G Ordering Codes

Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAML21G16B-AUT	64K	8K	TQFP48	Tape & Reel
ATSAML21G16B-MUT			QFN48	
ATSAML21G17B-AUT	128K	16K	TQFP48	Tape & Reel
ATSAML21G17B-MUT			QFN48	
ATSAML21G18B-AUT	256K	32K	TQFP48	Tape & Reel
ATSAML21G18B-MUT			QFN48	

3.3. SAM L21E

Table 3-3. SAM L21E

Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAML21E15B-AUT	32K	4K	TQFP32	Tape & Reel
ATSAML21E15B-MUT			QFN32	
ATSAML21E16B-AUT	64K	8K	TQFP32	Tape & Reel
ATSAML21E16B-MUT			QFN32	
ATSAML21E17B-AUT	128K	16K	TQFP32	Tape & Reel
ATSAML21E17B-MUT			QFN32	
ATSAML21E18B-AUT	256K	32K	TQFP32	Tape & Reel
ATSAML21E18B-MUT			QFN32	

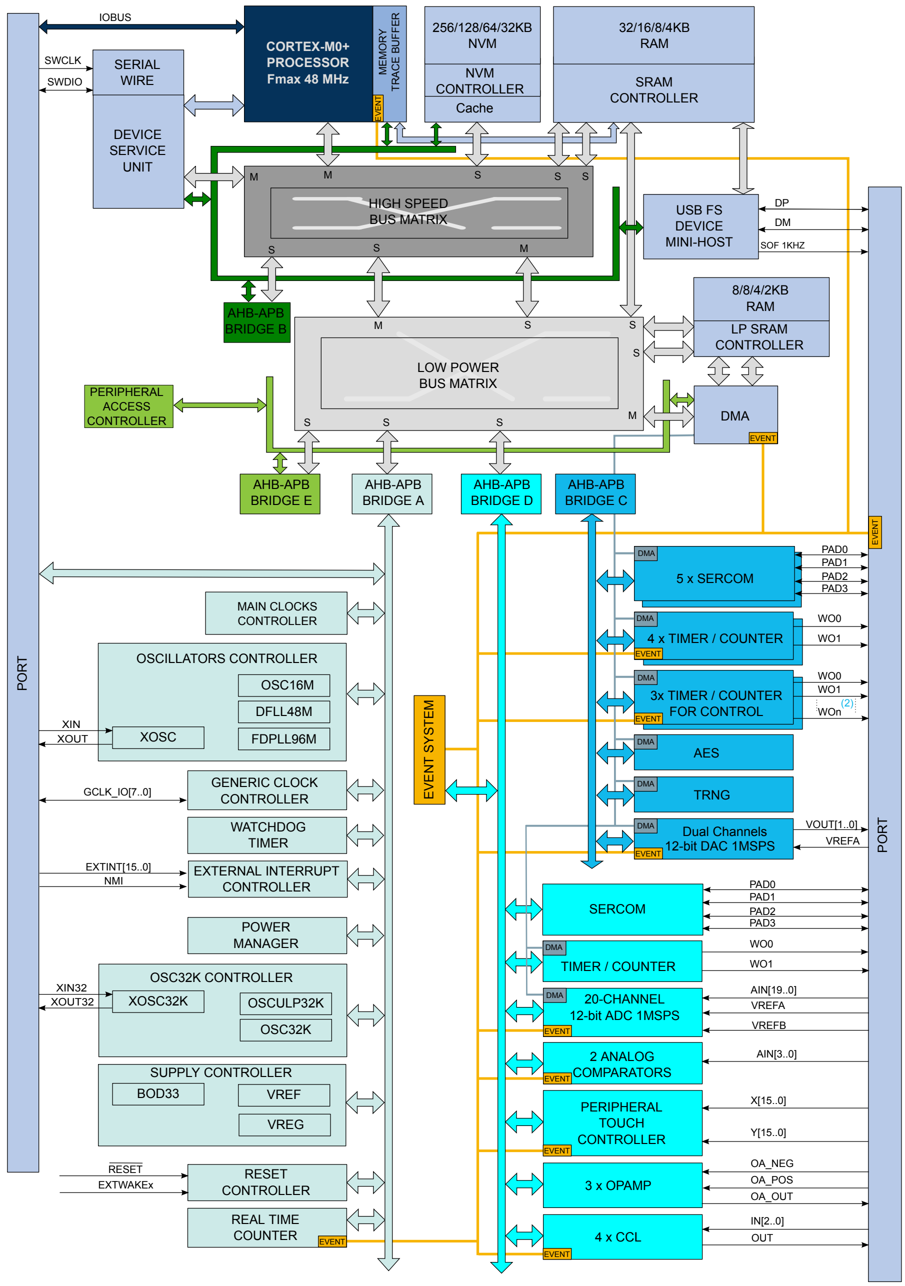
3.4. Device Identification

The DSU - Device Service Unit peripheral provides the Device Selection bits in the Device Identification register (DID.DEVSEL) in order to identify the device by software. The SAM L21 variants have a reset value of DID=0x1081drxx, with the LSB identifying the die number ('d'), the die revision ('r') and the device selection ('xx').

Table 3-4. SAM L21 Device Identification Values

DEVSEL (DID[7:0])	Device
0x00	SAML21J18A
0x01	SAML21J17A
0x02	SAML21J16A
0x03-0x04	Reserved
0x05	SAML21G18A

4. Block Diagram



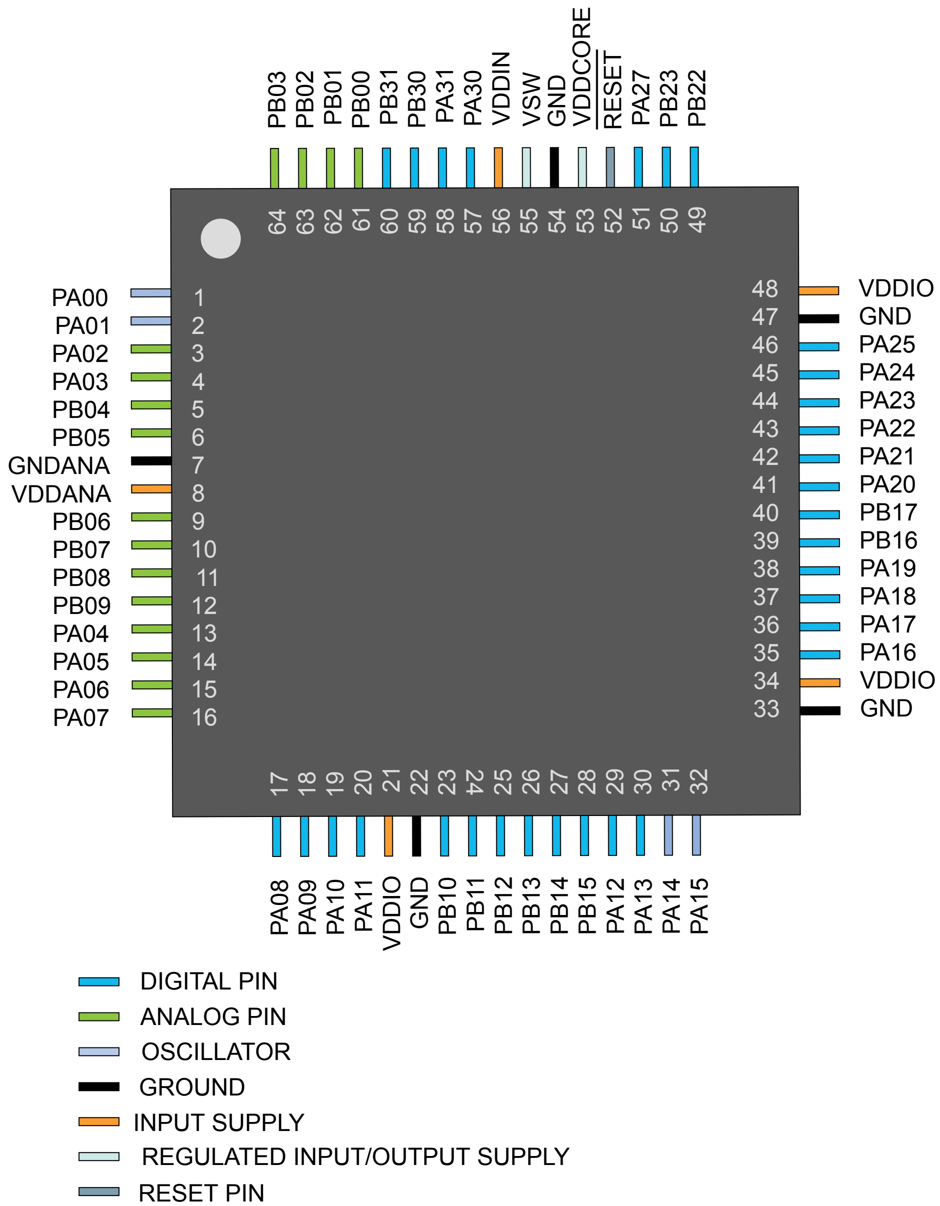
Note:

1. Some products have different number of SERCOM instances, Timer/Counter instances, PTC signals and ADC signals.

2. The three TCC instances have different configurations, including the number of Waveform Output (WO) lines.

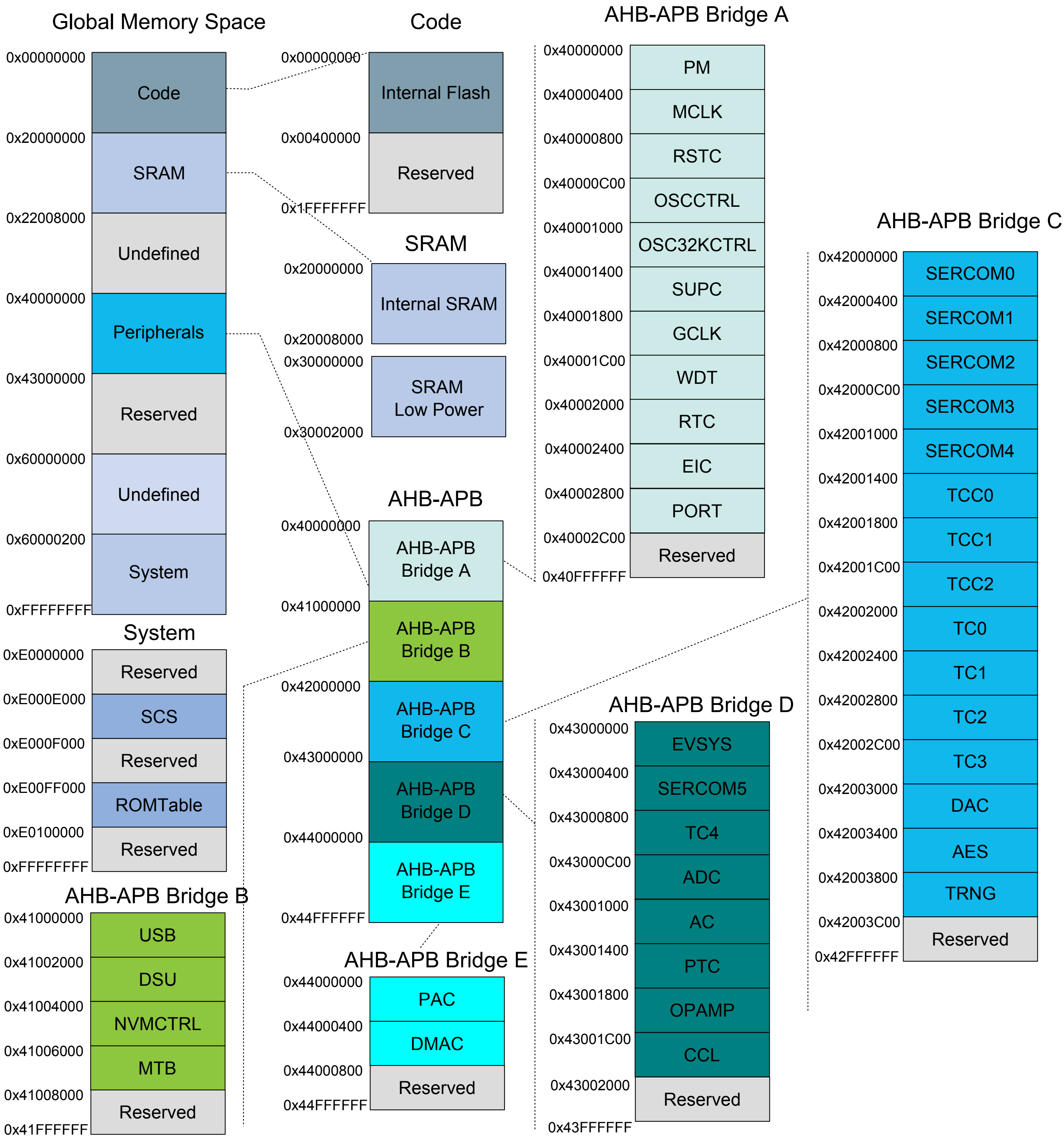
5. Pinout

5.1. SAM L21J



6. Product Mapping

Figure 6-1. Atmel SAM L21 Product Mapping



– External interrupt signals connect to the NVIC, and the NVIC prioritizes the interrupts. Software can set the priority of each interrupt. The NVIC and the Cortex-M0+ processor core are closely coupled, providing low latency interrupt processing and efficient processing of late arriving interrupts. Refer to the Cortex-M0+ Technical Reference Manual for details (http://www.arm.com).

  Note: When the CPU frequency is much higher than the APB frequency it is recommended to insert a memory read barrier after each CPU write to registers mapped on the APB. Failing to do so in such conditions may lead to unexpected behavior such as e.g. re-entering a peripheral interrupt handler just after leaving it.

- System Timer (SysTick)
  – The System Timer is a 24-bit timer clocked by CLK_CPU that extends the functionality of both the processor and the NVIC. Refer to the Cortex-M0+ Technical Reference Manual for details (http://www.arm.com).
- System Control Block (SCB)
  – The System Control Block provides system implementation information, and system control. This includes configuration, control, and reporting of the system exceptions. Refer to the Cortex-M0+ Devices Generic User Guide for details (http://www.arm.com)
- Micro Trace Buffer (MTB)
  – The CoreSight MTB-M0+ (MTB) provides a simple execution trace capability to the Cortex-M0+ processor. Refer to section MTB-Micro Trace Buffer and the CoreSight MTB-M0+ Technical Reference Manual for details (http://www.arm.com).

Related Links

Nested Vector Interrupt Controller on page 21

7.1.1.2. Cortex M0+ Address Map

Table 7-2. Cortex-M0+ Address Map

Address	Peripheral
0xE000E000	System Control Space (SCS)
0xE000E010	System Timer (SysTick)
0xE000E100	Nested Vectored Interrupt Controller (NVIC)
0xE000ED00	System Control Block (SCB)
0x41006000	Micro Trace Buffer (MTB)

7.1.1.3. I/O Interface

The device allows direct access to PORT registers. Accesses to the AMBA® AHB-Lite™ and the single cycle I/O interface can be made concurrently, so the Cortex M0+ processor can fetch the next instructions while accessing the I/Os. This enables single cycle I/O access to be sustained for as long as necessary.

7.2. Nested Vector Interrupt Controller

7.2.1. Overview

The Nested Vectored Interrupt Controller (NVIC) in the SAM L21 supports 32 interrupt lines with four different priority levels. For more details, refer to the Cortex-M0+ Technical Reference Manual (http://www.arm.com).

7.2.2. Interrupt Line Mapping

Each of the 28 interrupt lines is connected to one peripheral instance, as shown in the table below. Each peripheral can have one or more interrupt flags, located in the peripheral's Interrupt Flag Status and Clear (INTFLAG) register.

An interrupt flag is set when the interrupt condition occurs. Each interrupt in the peripheral can be individually enabled by writing a 1 to the corresponding bit in the peripheral's Interrupt Enable Set (INTENSET) register, and disabled by writing 1 to the corresponding bit in the peripheral's Interrupt Enable Clear (INTENCLR) register.

An interrupt request is generated from the peripheral when the interrupt flag is set and the corresponding interrupt is enabled.

The interrupt requests for one peripheral are ORed together on system level, generating one interrupt request for each peripheral. An interrupt request will set the corresponding interrupt pending bit in the NVIC interrupt pending registers (SETPEND/CLRPEND bits in ISPR/ICPR).

For the NVIC to activate the interrupt, it must be enabled in the NVIC interrupt enable register (SETENA/CLRENA bits in ISER/ICER). The NVIC interrupt priority registers IPR0-IPR7 provide a priority field for each interrupt.

Table 7-3. Interrupt Line Mapping

Peripheral source	NVIC line
EIC NMI – External Interrupt Controller	NMI
PM – Power Manager MCLK - Main Clock OSCCTRL - Oscillators Controller OSC32KCTRL - 32KHz Oscillators Controller SUPC - Supply Controller PAC - Protecion Access Controller	0
WDT – Watchdog Timer	1
RTC – Real Time Counter	2
EIC – External Interrupt Controller	3
NVMCTRL – Non-Volatile Memory Controller	4
DMAC - Direct Memory Access Controller	5
USB - Universal Serial Bus	6
EVSYS – Event System	7
SERCOM0 – Serial Communication Interface 0	8
SERCOM1 – Serial Communication Interface 1	9
SERCOM2 – Serial Communication Interface 2	10
SERCOM3 – Serial Communication Interface 3	11
SERCOM4 – Serial Communication Interface 4	12

Peripheral source	NVIC line
SERCOM5 – Serial Communication Interface 5	13
TCC0 – Timer Counter for Control 0	14
TCC1 – Timer Counter for Control 1	15
TCC2 – Timer Counter for Control 2	16
TC0 – Timer Counter 0	17
TC1 – Timer Counter 1	18
TC2 – Timer Counter 2	19
TC3 – Timer Counter 3	20
TC4 – Timer Counter 4	21
ADC – Analog-to-Digital Converter	22
AC – Analog Comparator	23
DAC – Digital-to-Analog Converter	24
PTC – Peripheral Touch Controller	25
AES - Advanced Encrytpion Standard module	26
TRNG - True Random Number Generator	27

7.3. Micro Trace Buffer

7.3.1. Features

- Program flow tracing for the Cortex-M0+ processor
- MTB SRAM can be used for both trace and general purpose storage by the processor
- The position and size of the trace buffer in SRAM is configurable by software
- CoreSight compliant

7.3.2. Overview

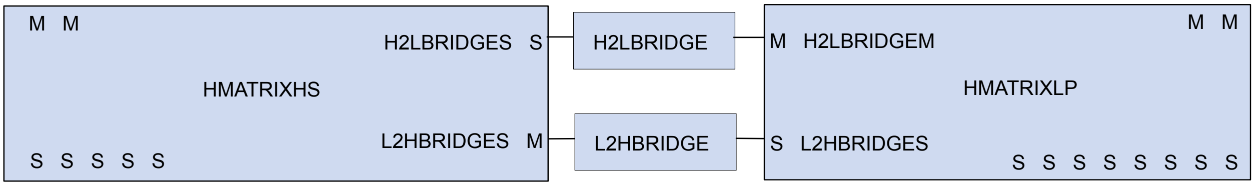
When enabled, the MTB records the changes in program flow that are reported by the Cortex-M0+ processor over the execution trace interface. This interface is shared between the Cortex-M0+ processor and the CoreSight MTB-M0+. The information is stored by the MTB in the SRAM as trace packets. An off-chip debugger can extract the trace information using the Debug Access Port to read the trace information from the SRAM. The debugger can then reconstruct the program flow from this information.

The MTB stores trace information into the SRAM and gives the processor access to the SRAM simultaneously. The MTB ensures that trace write accesses have priority over processor accesses.

An execution trace packet consists of a pair of 32-bit words that the MTB generates when it detects a non-sequential change of the program pounter (PC) value. A non-sequential PC change can occur during branch instructions or during exception entry. See the CoreSight MTB-M0+ Technical Reference Manual for more details on the MTB execution trace packet format.

Tracing is enabled when the MASTER.EN bit in the Master Trace Control Register is 1. There are various ways to set the bit to 1 to start tracing, or to 0 to stop tracing. See the CoreSight Cortex-M0+ Technical Reference Manual for more details on the Trace start and stop and for a detailed description of the MTB's

Figure 7-1. High-Speed Bus System Components



7.4.2. Configuration

Figure 7-2. Master-Slave Relations High-Speed Bus Matrix

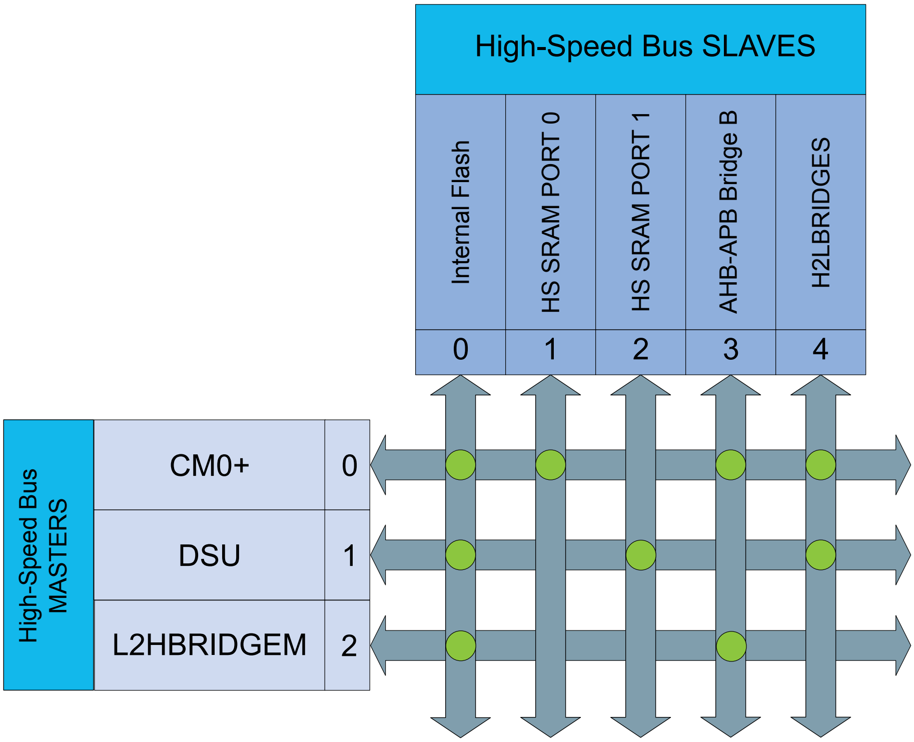
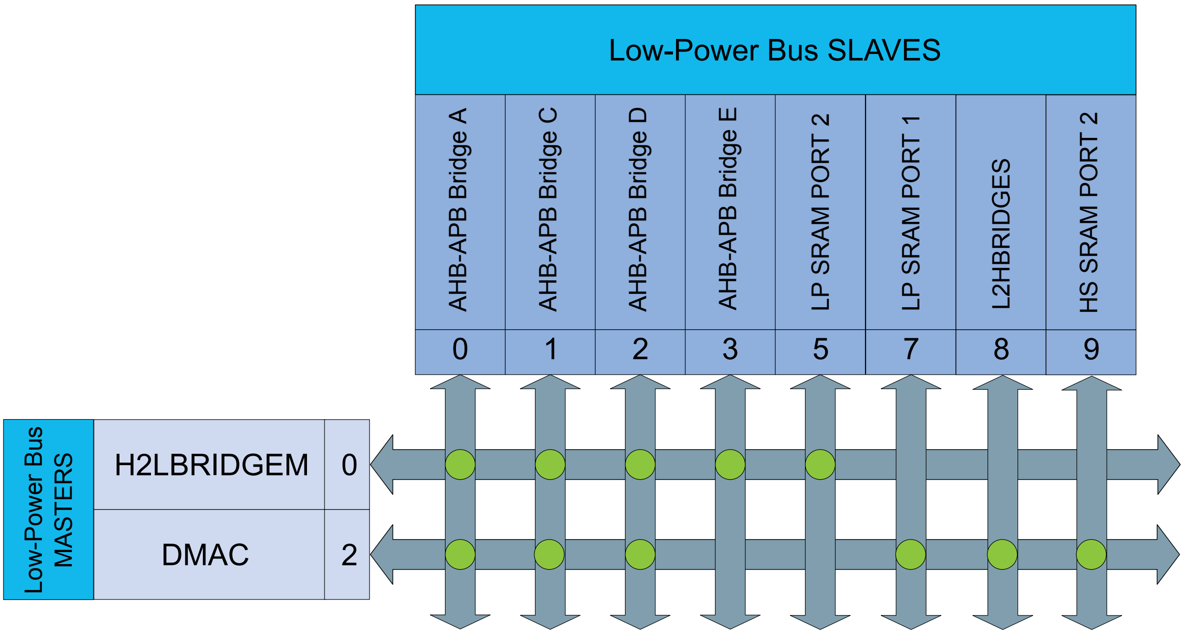


Figure 7-3. Master-Slave Relations Low-Power Bus Matrix



LP SRAM Port Connection	Port ID	Connection Type	QoS	default QoS
H2LBRIDGEM - HS to LP bus matrix AHB to AHB bridge	2	Bus Matrix	0x44000924[(1)], bits[1:0]	0x2
DMAC - Direct Memory Access Controller - Data Access	1	Bus Matrix	IP-QOSCTRL.DQOS	0x2

Note:

1. Using 32-bit access only.

8. Packaging Information

8.1. Thermal Considerations

8.1.1. Thermal Resistance Data

The following table summarizes the thermal resistance data depending on the package.

Table 8-1. Thermal Resistance Data

Package Type	θ_{JA}	θ_{JC}
32-pin TQFP	68°C/W	25.8°C/W
48-pin TQFP	78.8°C/W	12.3°C/W
64-pin TQFP	66.7°C/W	11.9°C/W
32-pin QFN	37.2°C/W	3.1°C/W
48-pin QFN	31.6°C/W	10.3°C/W
64-pin QFN	32.2°C/W	10.1°C/W
64-pin WLCSP	36.8°C/W	5.0°C/W

Related Links

Junction Temperature on page 29

8.1.2. Junction Temperature

The average chip-junction temperature, T_J, in °C can be obtained from the following:

1. $T_J = T_A + (P_D \times \theta_{JA})$
2. $T_J = T_A + (P_D \times (\theta_{HEATSINK} + \theta_{JC}))$

where:

- θ_{JA} = Package thermal resistance, Junction-to-ambient (°C/W), see Thermal Resistance Data
- θ_{JC} = Package thermal resistance, Junction-to-case thermal resistance (°C/W), see Thermal Resistance Data
- $\theta_{HEATSINK}$ = Thermal resistance (°C/W) specification of the external cooling device
- P_D = Device power consumption (W)
- T_A = Ambient temperature (°C)

From the first equation, the user can derive the estimated lifetime of the chip and decide if a cooling device is necessary or not. If a cooling device is to be fitted on the chip, the second equation should be used to compute the resulting average chip-junction temperature T_J in °C.

Related Links

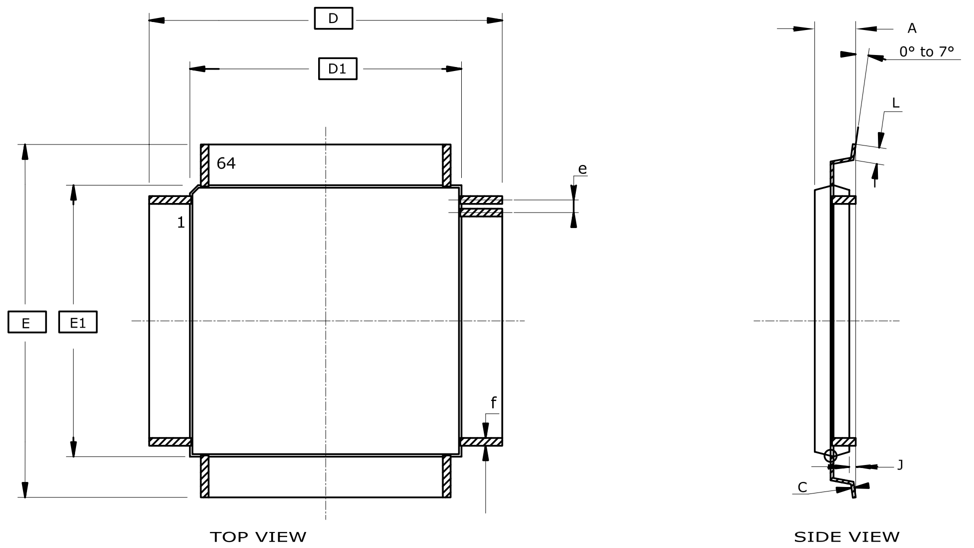
Thermal Resistance Data on page 29

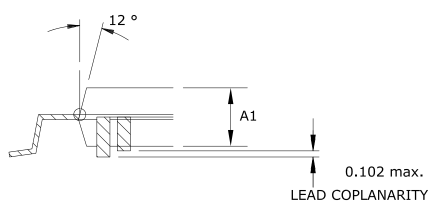
Table 8-4. Package Reference

JEDEC Drawing Reference	N/A
JESD97 Classification	E1

8.2.2. 64 pin TQFP

DRAWINGS NOT SCALED





COMMON DIMENSIONS

(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	-----	-----	1.20	
A1	0.95	-----	1.05	
C	0.09	-----	0.20	
D/E		12.00		
D1/E1		10.00		2
J	0.05	-----	0.15	
L	0.45	-----	0.75	
e		0.50 BSC		
f	0.17	-----	0.27	
n		64		

Notes :
1. This drawing is for general information only. Refer to JEDEC Drawing MS-026, Variation ACD.
2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is 0.25mm per side. Dimensions D1 and E1 are maximum plastic body size dimensions including mold mismatch.
3. Lead coplanarity is 0.10mm maximum.

05/03/2013

Atmel	TITLE	GPC	DRAWING NO.	REV.
Package Drawing Contact: **packagedrawings@atmel.com**	MF, 64 Lds - 0.50mm Pitch, 10x10x1.0mm Body size Thin Profile Plastic Quad Flat Package (TQFP)	AIN	MF	D

Table 8-5. Device and Package Maximum Weight

300	mg

Table 8-6. Package Characteristics

Moisture Sensitivity Level	MSL3

Table 8-7. Package Reference

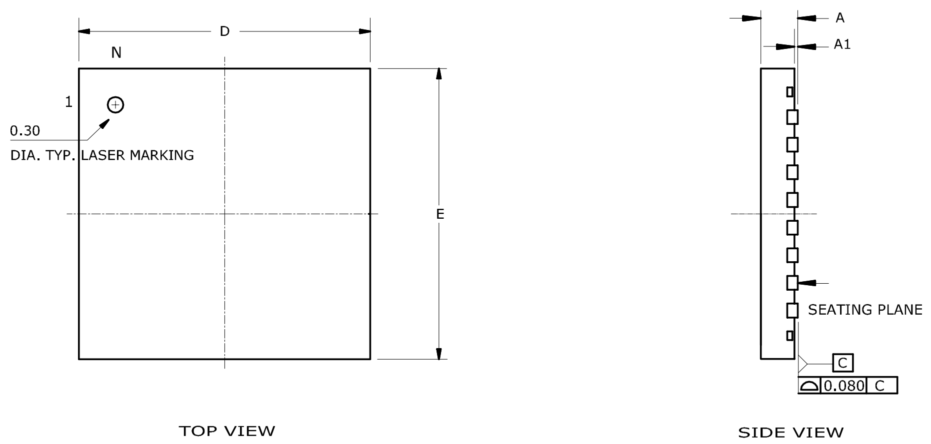
JEDEC Drawing Reference	MS-026
JESD97 Classification	E3

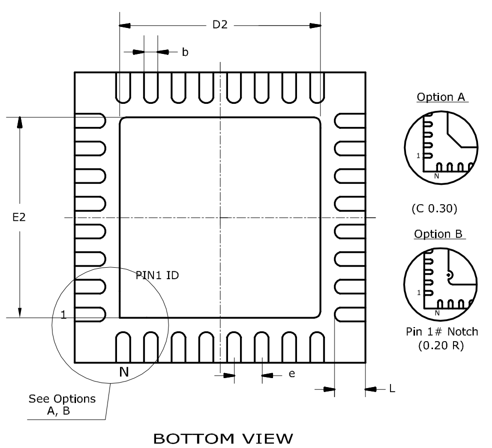
Table 8-19. Package Reference

JEDEC Drawing Reference	MS-026
JESD97 Classification	E3

8.2.7. 32 pin QFN

DRAWINGS NOT SCALED





COMMON DIMENSIONS

(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	0.80	----	1.00	
A1	0.00	----	0.05	
D/E		5.00 BSC		
D2/E2	3.50	3.60	3.70	
L	0.30	0.40	0.50	
b	0.18	0.25	0.30	2
e		0.50 BSC		
n		32		

Notes : 1. This drawing is for general information only. Refer to JEDEC Drawing MO-220, Variation VHHD-5, for proper dimensions, tolerances, datums, etc.
2. Dimension b applies to metallized terminal and is measured between 0.15mm and 0.30mm from the terminal tip.
If the terminal has the optical radius on the other end of the terminal, the dimension should not be measured in that radius area.

10/05/2015

	TITLE	GPC	DRAWING NO.	REV.
Atmel **Package Drawing Contact:** **packagedrawings@atmel.com**	PG, 32 Leads , 0.50mm pitch, 5x5x1.0mm Body Size Very Thin Quad Flat No Lead Package (VQFN) Sawn	ZKV	PG	C

Note: The exposed die attach pad is connected inside the device to GND and GNDANA.

Table 8-20. Device and Package Maximum Weight

90	mg

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